



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of:

NAKAJYO, Shinsuke et al.

Serial No.: 09/686,958

Filed: October 12, 2000

Group Art Unit: 2824

Examiner: Adam Pyonin

P.T.O. Confirmation No.: 5708

For. **MANUFACTURE OF WAFER LEVEL SEMICONDUCTOR DEVICE AND SEMICONDUCTOR DEVICE**

AMENDMENT

Commissioner for Patents
Washington, D.C. 20231

Date: January 3, 2003

Sir:

In response to the Office Action dated October 3, 2002, please amend the above-identified application as set forth below:

IN THE SPECIFICATION:

Amend the specification as follows:

(Page 13, lines 1-26):

thereafter attach the resin sheet having the marking to the rear surface of the wafer.

Thereby, the marking information including the position information and result of electrical test is not required to temporarily print unlike the first embodiment and the result of electrical test can be marked on the resin sheet simultaneously when the test is